

STPS30H100DJF

Power Schottky rectifier

Datasheet - production data

Features

- Very low conduction losses
- Low forward voltage drop
- Low thermal resistance
- High specified avalanche capability
- High integration
- ECOPACK[®]2 compliant component

Description

The STPS30H100DJF is a power Schottky rectifier suited for switch mode power supply and high frequency DC to DC converters.

Housed in a PowerFLAT™ package, this device is intended to be used in adaptors requiring good efficiency at both low and high load. Its low profile was especially designed to be used in applications with space-saving constraints.

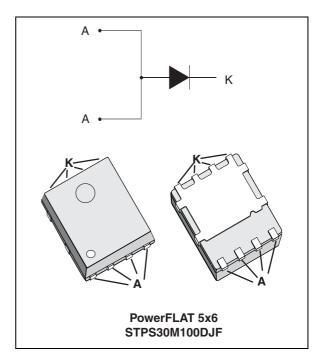


Table 1. Device summary

Symbol	Value
I _{F(AV)}	30 A
V_{RRM}	100 V
T _j	150 °C
V _F (typ)	0.56 V

TM: PowerFLAT is a trademark of STMicroelectronics

Characteristics STPS30H100DJF

1 Characteristics

Table 2. Absolute ratings (limiting values, anode terminals short circuited)

Symbol	Parameter	Value	Unit	
V_{RRM}	Repetitive peak reverse voltage		100	V
I _{F(RMS)}	Forward rms current		45	Α
I _{F(AV)}	Average forward current $\delta = 0.5$	30	Α	
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$		250	Α
P _{ARM}	Repetitive peak avalanche power $t_p = 1 \mu s$, $T_j = 25 ^{\circ}C$		3700	W
V _{ARM}	Maximum repetitive peak avalanche voltage	120	V	
T _{stg}	Storage temperature range	-65 to +175	°C	
T _j	Maximum operating junction temperature	150	°C	

^{1.} $\frac{dPtot}{dT_j} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case	2	°C/W

Table 4. Static electrical characteristics (anode terminals short circuited)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	, (1) Reverse leakage	T _j = 25 °C	V -V	-	-	6	μΑ
'R' current	T _j = 125 °C	$V_R = V_{RRM}$	-	2.5	6.5	mA	
	V (1) Famurad valtage dues	T _j = 25 °C	I _F = 15 A	-	-	0.76	>
V _E ⁽¹⁾		T _j = 125 °C		-	0.56	0.62	
V _F ⁽¹⁾ Forward voltage drop	T _j = 25 °C	I _F = 30 A	-	-	0.84	V	
	T _j = 125 °C		-	0.63	0.71		

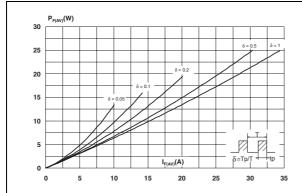
^{1.} Pulse test: $t_p = 380 \mu s$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.60 \times I_{F(AV)} + 0.00367 \times I_{F}^{2}_{(RMS)}$$

STPS30H100DJF Characteristics

Figure 1. Average forward power dissipation Figure 2. Average forward current versus versus average forward current ambient temperature (δ = 0.5)



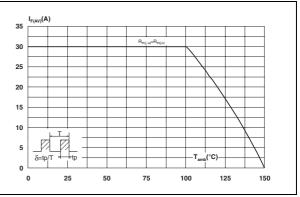
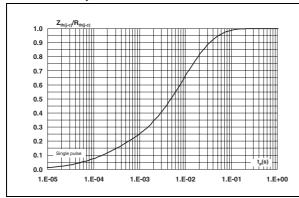


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

Figure 4. Reverse leakage current versus reverse voltage applied (typical values)



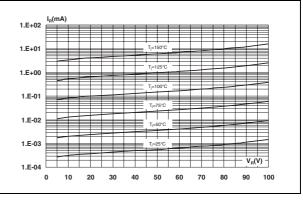
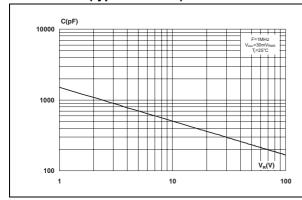
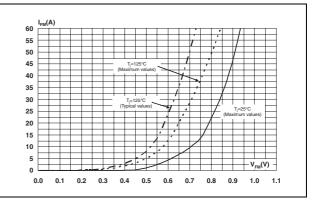


Figure 5. Junction capacitance versus reverse voltage applied (typical values)

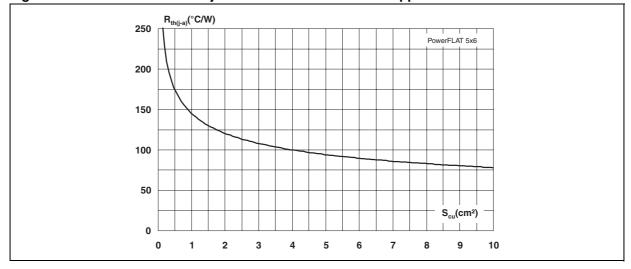
Figure 6. Forward voltage drop versus forward current





Characteristics STPS30H100DJF

Figure 7. Thermal resistance junction to ambient versus copper surface under tab



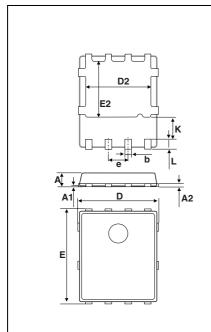
STPS30H100DJF Package information

2 Package information

- Epoxy meets UL94, V0
- Lead-free package

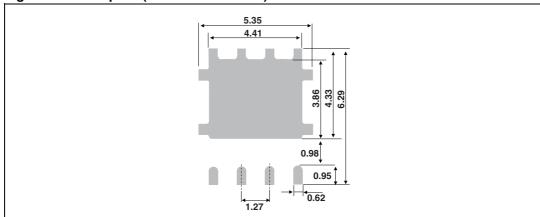
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 5. PowerFLAT 5x6 dimensions



	Dimensions					
Ref.	Millimeters		rs			
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	0.80		1.00	0.031		0.039
A1	0.02		0.05	0.001		0.002
A2		0.25			0.010	
b	0.30		0.50	0.012		0.020
D		5.20			0.205	
D2	4.11		4.31	0.162		0.170
е		1.27			0.050	
Е		6.15			0.242	
E2	3.50		3.70	0.138		0.146
L	0.50		0.80	0.020		0.031
K	1.275		1.575	0.050		0.062

Figure 8. Footprint (dimensions in mm)



Package information STPS30H100DJF

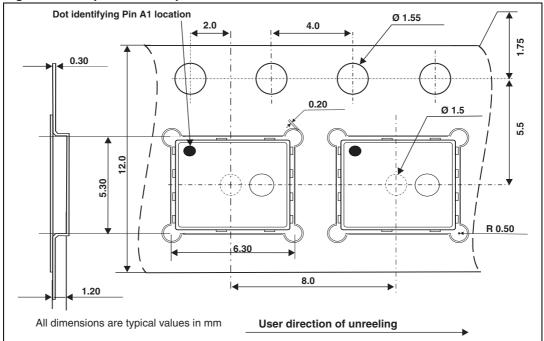


Figure 9. Tape and reel specifications

3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS30H100DJF-TR	PS30 H100	PowerFLAT 5x6	95 mg	3000	Tape and reel

4 Revision history

Table 7. Document revision history

Date	Revision	Changes
29-Mar-2012	1	Initial release.

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